

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (canceled).
2. (canceled).
3. (canceled).
4. (canceled).
5. (previously presented): A method of fabricating microstructures, the method comprising:  
preparing a substrate;  
forming an anti-stiction layer that is removed by dry etching for preventing stiction on the substrate;  
forming a sacrificial layer that is removed by wet etching on the substrate;  
removing parts of the anti-stiction layer and the sacrificial layer so that a part of the substrate is exposed and forming a resulting structure including a post; and  
forming at least one structure layer for forming at least one microstructure over the resulting structure.

6. (original): The method of claim 5, wherein the anti-stiction layer is formed of one of polymer and polycrystalline silicon.
7. (original): The method of claim 5, wherein the anti-stiction layer is formed of photoresist.
8. (original): The method of claim 5, wherein the sacrificial layer is formed of one selected from the group consisting of phosphosilicate glass (PSG), silicon oxide, low temperature oxide, copper, iron, molybdenum, nickel, chrome, and tetraethylorthosilicate glass (TEOS).
9. (previously presented): A method for fabricating microstructures, the method comprising:
  - preparing a substrate;
  - forming an anti-stiction layer on the substrate;
  - forming a sacrificial layer on the anti-stiction layer;
  - forming at least one structure layer for creating at least one microstructure on the sacrificial layer; and
  - removing the sacrificial layer by wet etching and removing the anti-stiction layer by dry etching in order to release the at least one microstructure while preventing stiction.
10. (original): The method of claim 9, wherein the anti-stiction layer is formed of one of polymer and polycrystalline silicon.

11. (original): The method of claim 9, wherein the anti-stiction layer is formed of photoresist.
12. (original): The method of claim 9, wherein the sacrificial layer is formed of one selected from the group consisting of phosphosilicate glass (PSG), silicon oxide, low temperature oxide, copper, iron, molybdenum, nickel, chrome, and tetraethylorthosilicate glass (TEOS).
13. (canceled).
14. (canceled).
15. (currently amended): A method of fabricating microstructures, the method comprising:
  - preparing a substrate;
  - forming a sacrificial layer on the substrate;
  - forming an anti-stiction layer on the ~~sacrificial~~ sacrificial layer; and
  - forming at least one structure layer for forming at least one microstructure on the anti-stiction layer and removing the ~~sacrificial~~ sacrificial layer by wet etching while removing the anti-stiction layer by dry etching in order to release the at least one microstructure while preventing stiction.